<table>
<thead>
<tr>
<th>ALL ARTWORK VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-01492</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>LAYER NAME = M1 Board Outline</td>
<td>TID #: TIDA-01492</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Bottom Layer</td>
<td>GENERATED: 11/27/2017 4:04:59 PM</td>
<td></td>
<td>TEXAS INSTRUMENTS</td>
</tr>
</tbody>
</table>
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